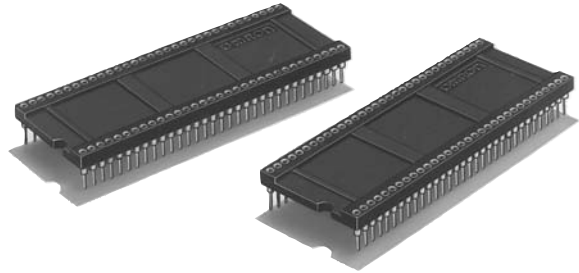


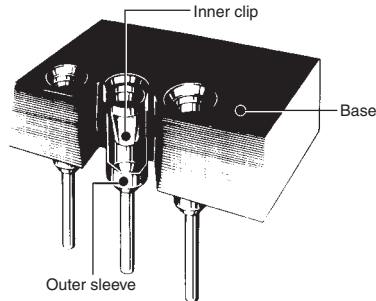
IC Socket for Shrink ICs.

- IC socket designed exclusively for shrink ICs with 1.778-mm contact pitch.
- Round-pin types for long life and good for shock and vibration durability.
- No flux rise.

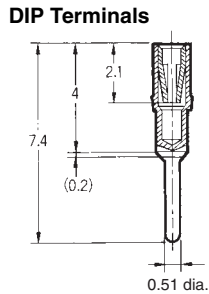
RoHS Compliant



Construction



Contact Dimensions (unit: mm)



Ratings and Characteristics

Rated voltage	1 A
Rated current	150 VAC
Contact resistance	20 mΩ max. (at 20 mV, 100 mA max.)
Insulation resistance	1,000 MΩ min. (at 500 VDC)
Dielectric strength	500 VAC for 1 min (leakage current: 1 mA max.)
Insertion force	3.92 N max. (with test gauge, 0.432 mm dia.)
Removal force	0.64 N min. (with test gauge, 0.432 mm dia.)
Insertion durability	100 times (with 0.75-μm gold plating) 50 times (with 0.25-μm gold plating)
Ambient operating temperature	- 55 to 125°C (with no condensation or icing)

Materials and Finish

Base	PET (UL94 V-0)/black
Inner clips	Beryllium copper/nickel base, 0.75-μm gold plating
Outer sleeves	Brass/nickel base, gold flash plating

Applicable IC Lead Dimensions

Lead	Depth × width (mm)	
Flat leads	0.29 ±0.09 × 0.46 ±0.08 (See note 1.)	
Round leads	0.53 dia. max.	0.41 dia. min.

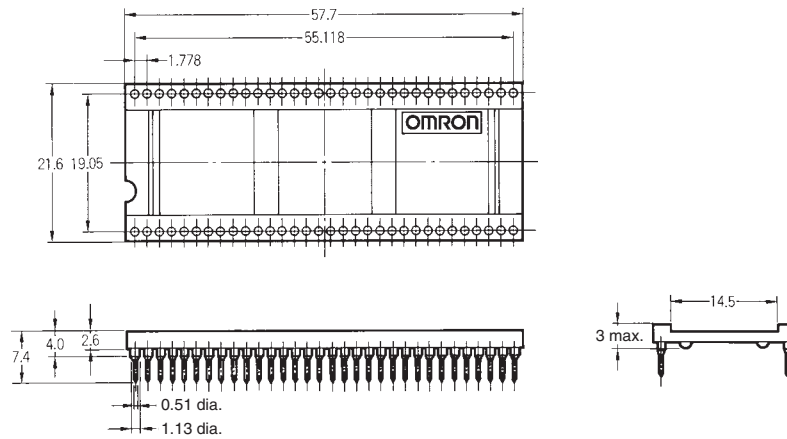
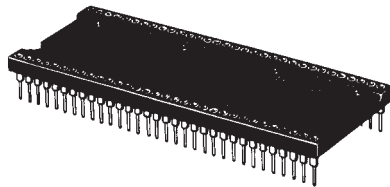
- Note:**
1. Do not use wire where diagonal is more than 0.56 mm.
 2. IC lead length of 3 mm or more (If the lead terminal is too long, the IC may rise up.)

XR3G Shrink IC Sockets

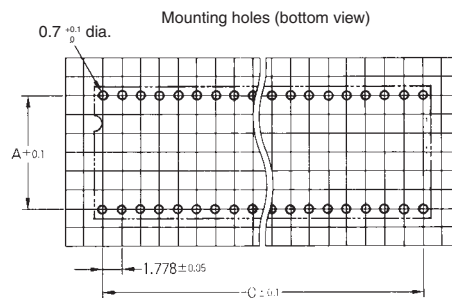
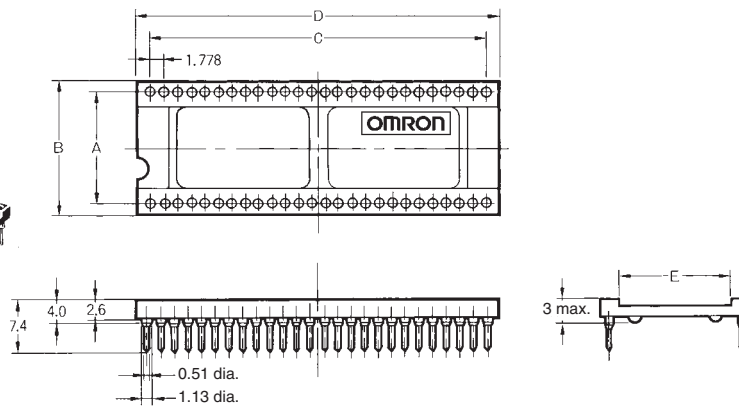
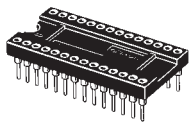
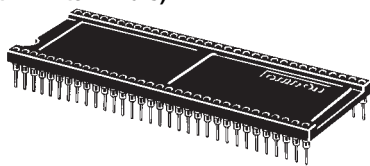
■ Dimensions

(unit: mm)

XR3G-64□1
(With DIP terminals)



XR3G-28□1
XR3G-32□1
XR3G-42□1
XR3G-52□1
(With DIP terminals)



Dimensions

No. of contacts	Dimensions (mm)				
	A	B	C	D	E
28	10.16	12.7	23.114	25.7	5.6
32	10.16	12.7	26.670	29.2	5.6
42	15.24	17.8	35.560	38.1	10.7
52	15.24	17.8	44.450	47.0	10.7
64	19.05	21.6	55.118	57.7	14.5

■ Ordering Information

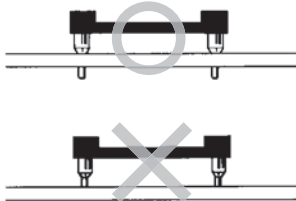
No. of contacts	Sockets with 0.25- μ m gold plating	Sockets with 0.75- μ m gold plating
28	XR3G-2811	XR3G-2801
32	XR3G-3211	XR3G-3201
42	XR3G-4211	XR3G-4201
52	XR3G-5211	XR3G-5201
64	XR3G-6411	XR3G-6401

■ Precautions

Correct Use

Soldering

- When soldering, make sure that the outer sleeve of the IC Socket does not stick out of the circuit board through-holes.



- Make sure that no flux enters the IC Socket from the top.

Automated Soldering Conditions (Jet Flow)

1. Soldering temperature: $250 \pm 5^{\circ}\text{C}$
2. Continuous soldering time: Within 5 ± 1 s

• Application examples provided in this document are for reference only. In actual applications, confirm equipment functions and safety before using the product.
• Consult your OMRON representative before using the product under conditions which are not described in the manual or applying the product to nuclear control systems, railroad systems, aviation systems, vehicles, combustion systems, medical equipment, amusement machines, safety equipment, and other systems or equipment that may have a serious influence on lives and property if used improperly. Make sure that the ratings and performance characteristics of the product provide a margin of safety for the system or equipment, and be sure to provide the system or equipment with double safety mechanisms.

Note: Do not use this document to operate the Unit.

OMRON Corporation
ELECTRONIC AND MECHANICAL COMPONENTS COMPANY

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